

# Electronics, common issues

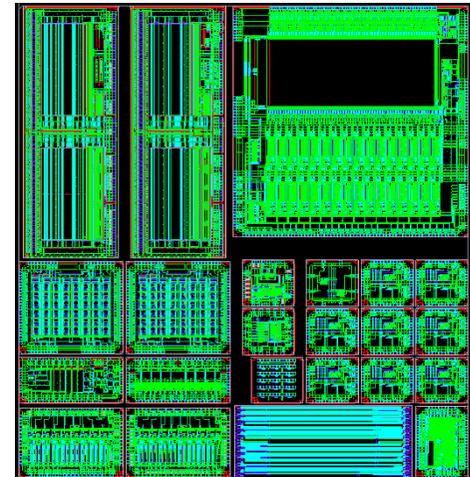
## NA2, JRA1, JRA2, JRA3

- Monday 8/10 16.30 hrs-18.00 hrs
- ~40 attendees
- NA2: News on the MICELEC microelectronics service; Michael Campbell for Alessandro Marchioro
- JRA1: The EUDET data reduction board and its application to the JRA1 pixel telescope; Concezio Bozzi
- JRA3: JRA3 developments; Christoph de la Taille
- JRA2: Requirements/ideas for a future gas detector readout device; Michael Campbell

# NA2 contribution

## EUDET-MICELEC Status Report October 2007

A. Marchioro / CERN-PH



# Technology access

- **Foundry contract** for 130 and 90 nm CMOS and BiCMOS is available for all HEP community
- Present total demand from community is below threshold to organize **internal MPWs**
  - But mini-MPWs (10-25 mm<sup>2</sup>) in 130 nm are organized through MOSIS for same foundry
- Proposal for **common 130 nm MPW run:**
  - **February 2008**
  - If interested, contact us asap !

# Support services

- **Packaging** contract discussed with Europractice for ASE/Taiwan
  - Many standard and advanced products DIL, Quad, BGA, Flip-Chip etc.
  - If interested, contact us!
- CERN has acquired a **new advanced IC tester** (Credence Sapphire)
  - Users interested in accessing this service for professional IC characterization are welcome to contact us!

# Tools and Training

- **Customized design kit** developed (partly) with EUDET funds to facilitate design of complex digital ICs
- Four **training courses** with 10 participants each (last in June 2007) organized to spread knowledge about utilization of advanced design tools. 5<sup>th</sup> Design course being prepared for late '07

## Final remarks:

Community is warmly recommended not to spread (the thin resources) over different technologies!

Users are welcome to submit suggestions and comments on their wishes and needs

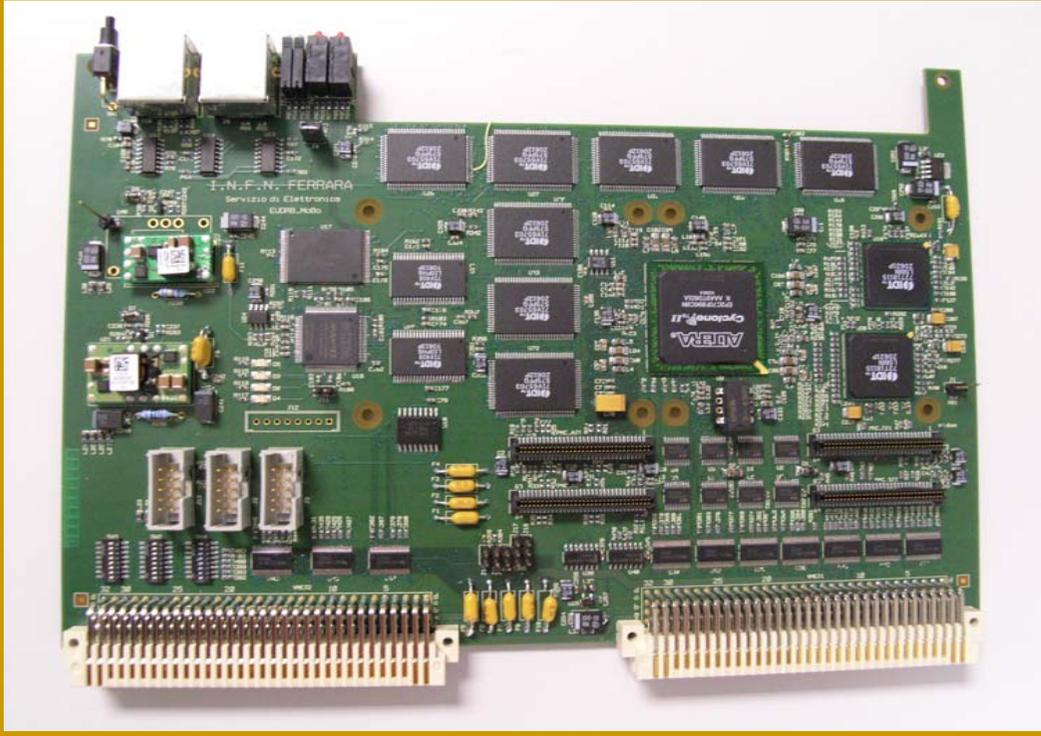
## Contribution from JRA1

**EUDRB: the data reduction board of the  
EUDET pixel telescope**

Lorenzo Chiarelli, Angelo Cotta Ramusino,  
Livio Piemontese, Davide Spazian  
Università & INFN Ferrara

Presented by Concezio Bozzi

# A VME64x/USB2.0-based DAQ card for MAPS sensors



Mother board built around an ALTERA Cyclone II FPGA (clock rate: 80MHz)

NIOS II, 32 bit “soft” microcontroller (clock rate: 40MHz) implemented in the FPGA for

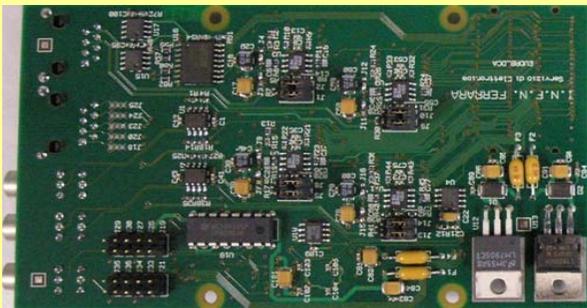
- on board diagnostics
- on-line calculation of pixel pedestal and noise
- remote configuration of the FPGA via RS-232, VME, USB2.0

Two readout modes:

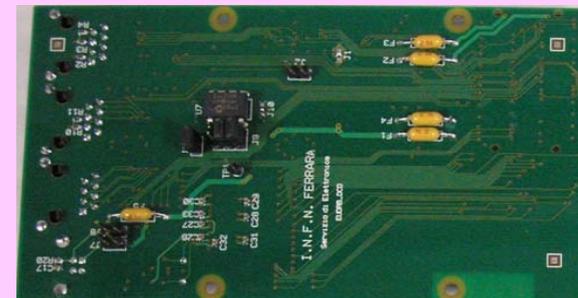
Zero Suppressed readout

Non Zero Suppressed readout

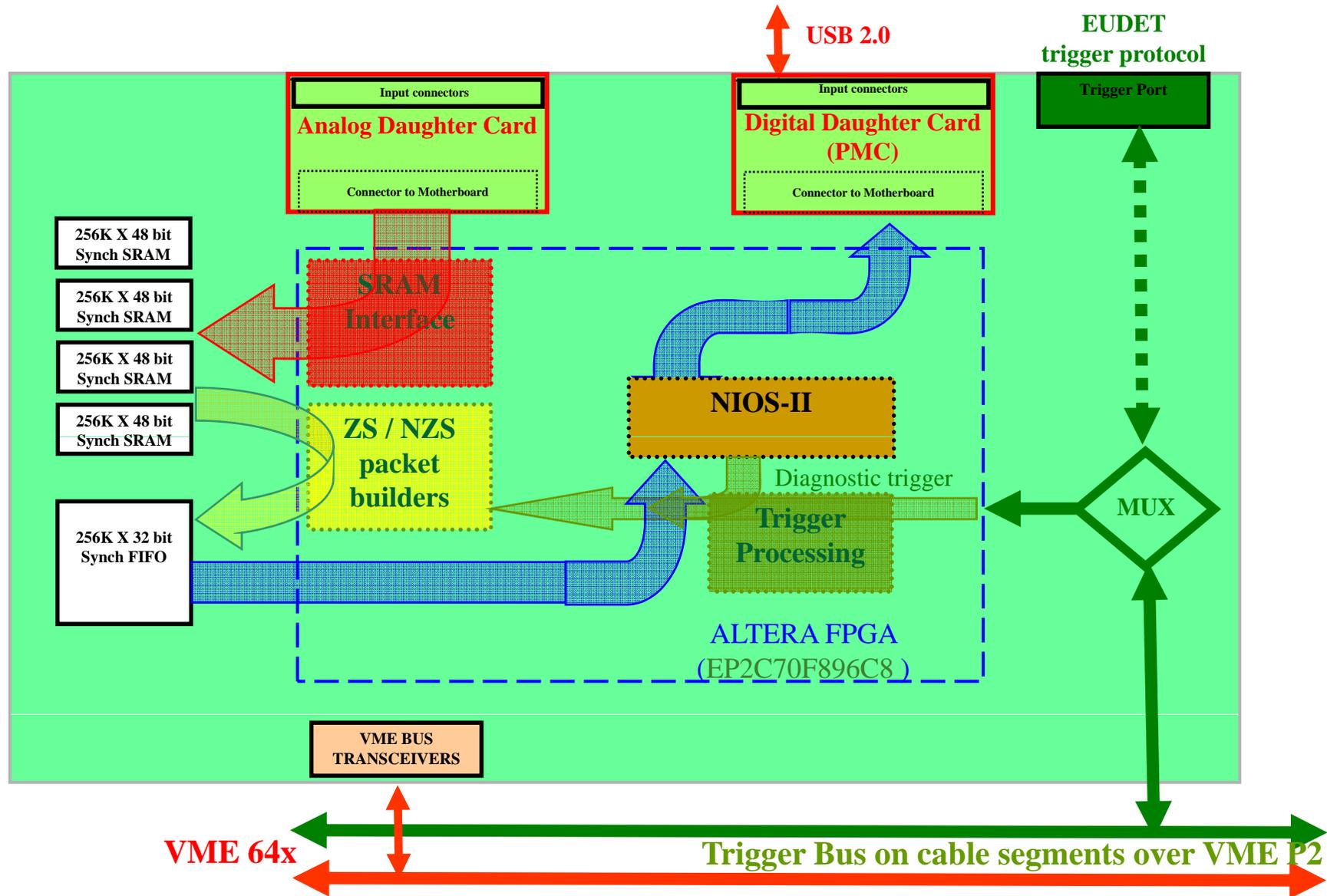
analog daughter card based on the successful LEPSI and SUCIMA designs



digital daughter card drives/receives control signals for the detectors and features a USB 2.0 link



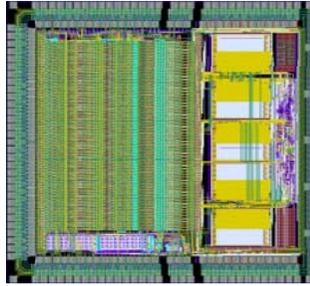
# Data Flow for benchtop DAQ via USB2.0, and for data taking via VMEBUS



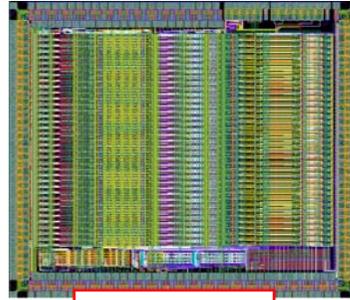
# Conclusions

- EUDRB successfully used in beam tests at DESY (June, August) and CERN (September)
- Connected to MAPS sensor for demonstrator: MimoTEL, 256x256, 30 $\mu$ m x 30 $\mu$ m pitch
- Hunting for better performance:
  - VME CPU is the real bottleneck at the moment
  - Some improvements on the EUDRB side also possible

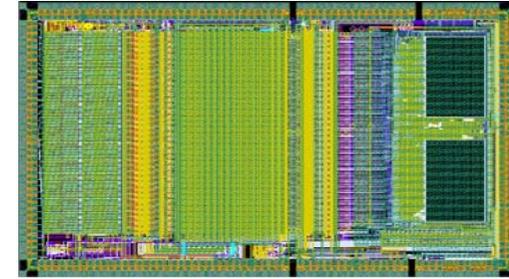
Once optimised, the EUDRB could be used in other Pixel read-out applications



HaRDROC



SKIROC



SPIROC

# EUDET JRA3 Front-End electronics in 2007



IN2P3  
INSTITUT NATIONAL DE PHYSIQUE NUCLEAIRE  
ET DE PHYSIQUE DES PARTICULES

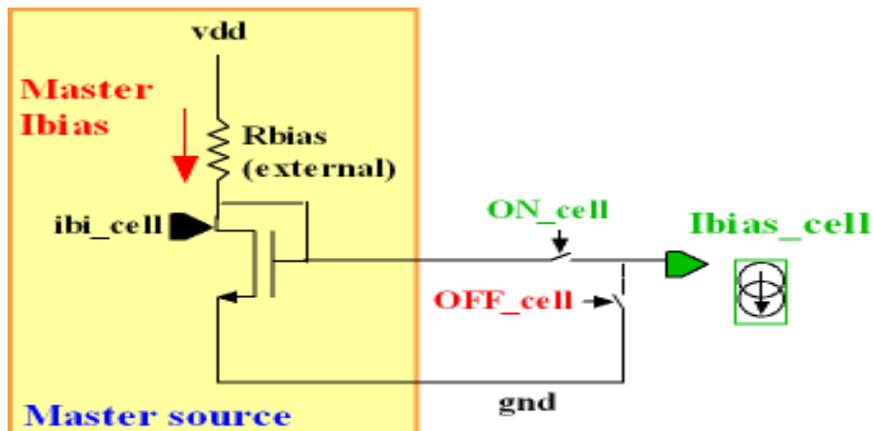
C. de La Taille  
IN2P3/LAL Orsay





# HARDROC POWER PULSING: Power dissipation

- Maximum power available:
  - 10  $\mu\text{W}$ / channel with 0.5% duty cycle
  - =>  $640\mu\text{W}/3.5\text{V} = \mathbf{180\ \mu\text{A}}$  for the entire chip
  - **OFF**= Ibias \_cell switched off during interbunch:



	ON	OFF
Vdd_pad	0	
Vdd_pa	5.8 mA	5.6 $\mu\text{A}$
Vdd_fsb	4.9 mA	65 $\mu\text{A}$
Vdd_d0	2.8 mA	78 $\mu\text{A}$
Vdd_d1	2.7 mA	0
Vddd+ vddd2	3.3mA	200 $\mu\text{A}$ + 0 (Clk OFF)
Vdd_dac	0.77 mA	218 $\mu\text{A}$
Vdd_bandga p	5.05 mA	2.73 mA
Total (noPP)	25.3 mA	3.2mA
Total with 0.5% PP	125 $\mu\text{A}$	0 hopefully

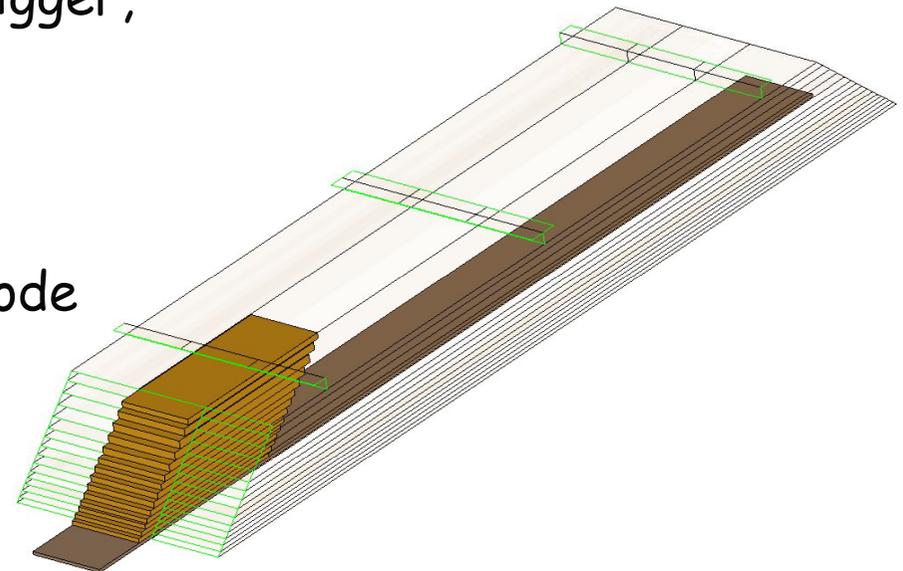
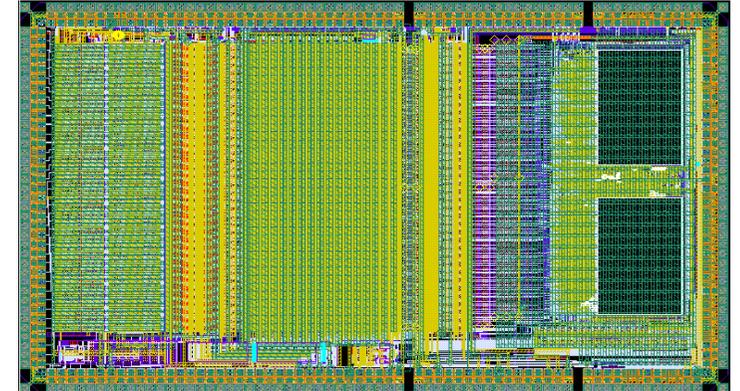
# Common issues

- Power pulsing studies
  - Power management and distribution
  - Stability,
  - Clock distribution
- DAQ
  - Zero suppressed data
  - Minimum number of lines
- ASIC technologies
  - « Analog friendly » technologies : now mostly 0.35 $\mu$ m AMS SiGe
  - Sharing blocks, MPWs : in2p3, Krakow....



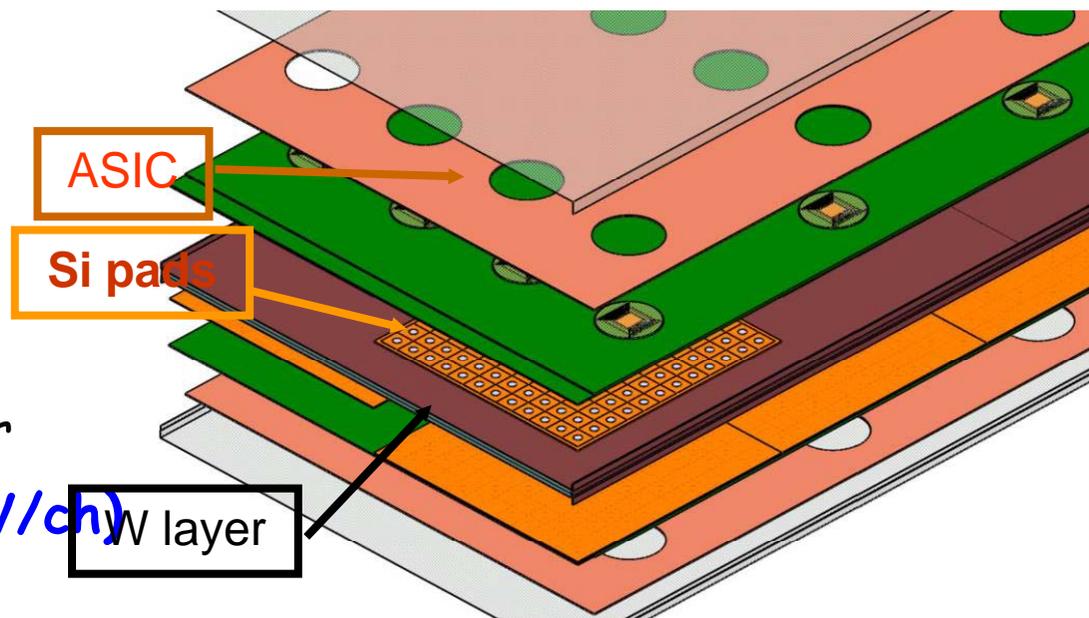
# Conclusion

- 3 major second generation ASICs for technological prototypes submitted
  - HARdROC submitted for DHCAL RPCs
  - SKIROC submitted for ECAL Si-W
  - SPIROC for AHCAL SiPM
- System aspects now proceeding
  - Power pulsing, Zero-suppress, Auto-trigger, 2<sup>nd</sup> generation DAQ...
  - On detector boards
  - Connection to DAQ : task force
  - EUDET repository for shared VHDL code

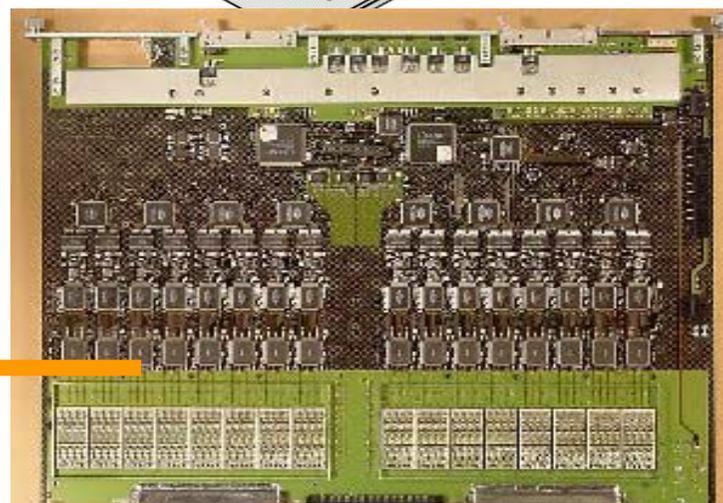
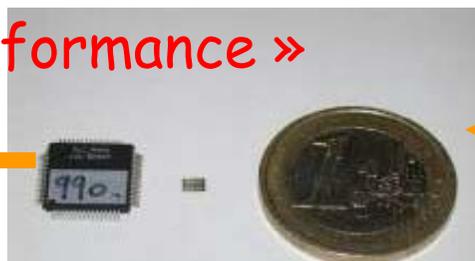


# ILC Challenges for electronics

- Requirements for electronics
  - Large dynamic range (15 bits)
  - Auto-trigger on  $\frac{1}{2}$  MIP
  - On chip zero suppress
  - Front-end embedded in detector
  - **Ultra-low power : (  $\ll 100\mu\text{W}/\text{ch}$  )**
  - $10^8$  channels
  - **Compactness**



- « Tracker electronics with calorimetric performance »



ILC :  $100\mu\text{W}/\text{ch}$

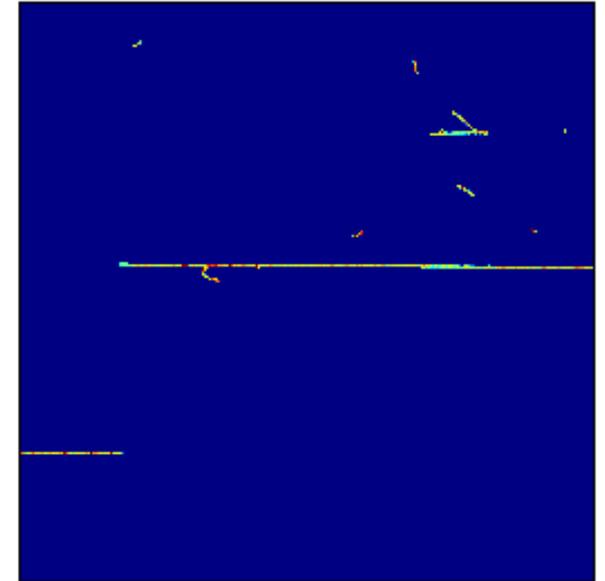
FLC\_PHY3 18ch 10\*10mm  $5\text{mW}/\text{ch}$

ATLAS LAr FEB 128ch 400\*500mm  $1\text{W}/\text{ch}$

## Contribution from JRA2

Pixel Readout Electronics -  
from HEP to imaging to HEP...  
Status, requirements, new ideas

M. Campbell, R. Ballabriga, E. Heijne, X. Llopart,  
L. Tlustos, W. Wong  
CERN  
Geneva, Switzerland



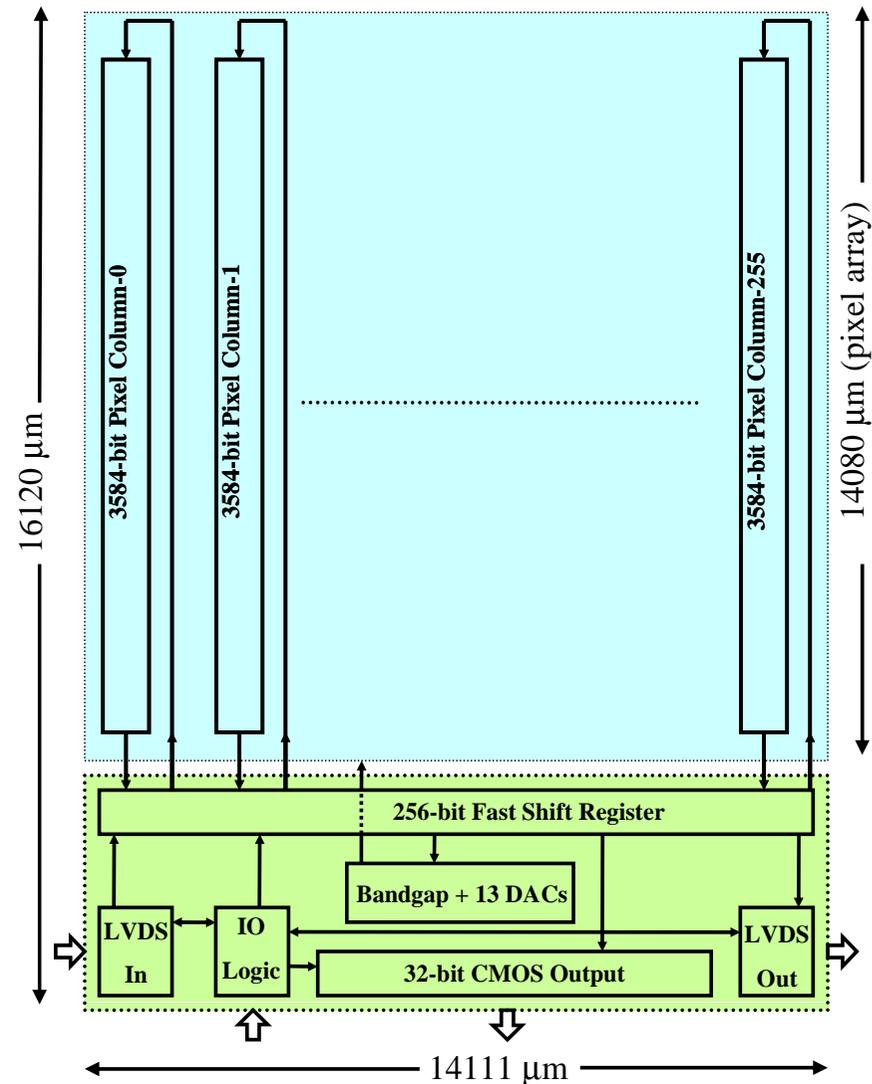
# Timepix developed within JRA2

- ◆ Chip architecture almost identical to Mpix2MXR20
  - M0=M1=1 and Shutter ON -> FClock used as Ref\_Clk
- ◆ 256x256 55 $\mu$ m square pixels
- ◆ Analog Power -> 440mW
- ◆ Digital Power (Ref\_Clk=50MHz) -> 220mW
- ◆ Serial readout (@100MHz) -> 9.17 ms
- ◆ Parallel readout (@100MHz) -> 287  $\mu$ s
- ◆ > 36M Transistors

Very successful development => JRA2 results

## Room for further development

- Charge below threshold in shared events is lost in all modes
- Charge measurement near to threshold in TOT is imprecise
- Arrival time/TOT measurement range is limited by counter depth
- Chip is neither triggerable nor data driven
- There is no FAST-OR



Michael Campbell

# Requirements for a general purpose gas and semiconductor readout chip

- Clean hit information
- Low and uniform threshold
- High spatial resolution
- Combined energy and arrival time information
- Include a FAST-OR

# GasSiPix - Front end

\*\*\* Basic idea developed together with Ruud Kluit of NIKHEF \*\*\*

- Medipix3 or GOSSIPO-2 like
  - Suitable for semiconductors and gas readout?
  - Rise time 25ns?
  - Noise 100 e<sup>-</sup> rms?
  - Minimum threshold 750e<sup>-</sup>?
  - Power <1W/cm<sup>2</sup>?
- For gas detectors include spark protection and SiProt shielding
  - Which A:Si thickness?
  - How many pC should it withstand?
- Use precision time tag unit from Nikhef (GOSSIPO-2 V. Gromov) in pixel to measure arrival time
  - 1-2ns precision for Vernier counter?
  - 15-bit clock tick counter?
- Use TOT for energy measurement and/or timewalk correction if charge summing not include
  - 8-bit TOT precision?

**Gave rise to a lively discussion, with clear interest in the subject**

# Summary of Common electronics session

- There is a broad spectrum of electronics activities in EUDET
- ~20 talks on electronics during the parallel sessions on Monday
- Some of these were discussed at the Common electronics session, with a view of common use/developments and cross fertilisation
- Clear areas for use across the NA/JRA's were indicated as well as prime areas for development and future application of EUDET work